# Loss Study: Host Backplane Channels & Packages

Howard Heck, Intel

March, 2018

IEEE 802.3 100Gb/s per Lane Electrical Study Group

#### Supporters

Rich Mellitz, Samtech Liav Ben Artsi, Marvell Technology

#### Intro

#### • Context

- 35dB-36dB discussed as max bump-bump loss
- 4dB proposed budget for package
- Questions
  - Can we meet 4dB IL for server packages?
  - Can we fit the backplane channel & 2 packages into a 35dB-36dB budget?

#### Summary

- Expect >5dB package loss
  - Not including Cd, Cp
  - 30mm length
  - 90C temperature
  - Next gen dielectric (50% loss) & surface roughness (50% reduction)
  - Trace geometries for server CPUs are limited by other interfaces (e.g. DRAM)
- Fitting in a 26dB budget will require trade-offs
  - Conventional: <15" ⊗
  - Cabled:  $4+'' AIC, \leq 0.8m$  cable
  - Orthogonal 4+" AIC

## Package Insertion Loss

- Our best expected insertion loss is 5dB for a 30mm package (Traces only)
  - Measured in the lab.
  - Only accounts for traces. Cp, Cd will add IL.
- Design
  - Next gen dielectric ~50% reduction in loss tangent
  - Next gen surface roughness ~50% reduction
- Environment: 90C temperature.
  - The delta between 25C and 90C is ~1dB for a 30mm package.



# Backplane Channel Insertion Loss

# **Conventional Backplane**

- Trace Lengths
  - CN & Switch: 0.5"-3"
  - BP: 1" 10"
- PCB material: MEG7N
- PCB Impedance:  $85\Omega$ ,  $93\Omega$ ,  $100\Omega$
- 0.093" PCB thickness
- 56G Backplane Connector
- Routes include breakout, vias
- 900 channels total



#### **Conventional Channel Response**





Total PCB length <15" at best.

# Cabled Backplane

- Trace Lengths
  - CN & Switch: 0.5"-3"
  - Cable: 0.033m 0.99m
- PCB material: MEG7N
- PCB Impedance: 85 $\Omega$ , 93 $\Omega$ , 100 $\Omega$
- 0.093" PCB thickness
- 56G Connector & 30AWG cable
- Routes include breakout, vias
- 730 channels total



#### Cabled Channel Response



Cabled backplane channel can work with 26dB-28dB.



# Orthogonal Backplane

- Trace Lengths
  - CN & Switch: 0.5"-3"
- PCB material: MEG7N
- PCB Impedance: 85 $\Omega$ , 93 $\Omega$ , 100 $\Omega$
- 0.093" PCB thickness
- 56G Connector
- Routes include breakout, vias
- 90 channels total

## Orthogonal Channel Response



Orthogonal backplane with longer card routes will fit in a 26dB budget.

#### Summary

- Expect >5dB package loss
  - Not including Cd, Cp
  - 30mm length
  - 90C temperature
  - Next gen dielectric (50% loss) & surface roughness (50% reduction)
  - Trace geometries for server CPUs are limited by other interfaces (e.g. DRAM)
- Fitting in a 26dB budget will require trade-offs
  - Conventional: <15" ⊗
  - Cabled:  $4+'' AIC, \leq 0.8m$  cable
  - Orthogonal 4+" AIC

# Thank you!

#### Channel IL Contours

